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May 2014



# FGB3040G2\_F085 / FGD3040G2\_F085 FGP3040G2\_F085 / FGI3040G2\_F085

## EcoSPARK<sup>®</sup> 2 300mJ, 400V, N-Channel Ignition IGBT

### Features

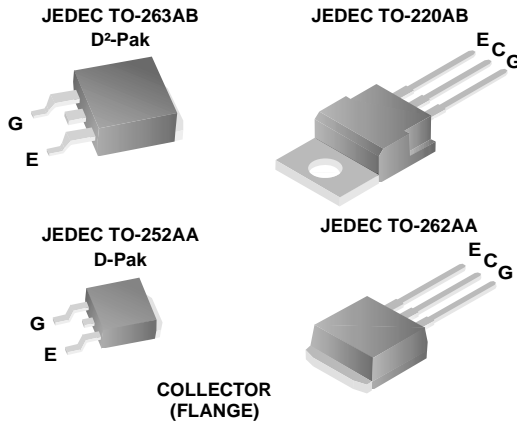
- SCIS Energy = 300mJ at  $T_J = 25^\circ\text{C}$
- Logic Level Gate Drive
- Qualified to AEC Q101
- RoHS Compliant

### Applications

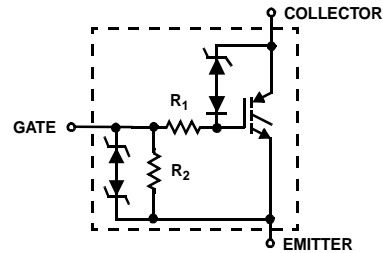
- Automotive Ignition Coil Driver Circuits
- Coil On Plug Applications



### Package



### Symbol



### Device Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$BV_{CER}$	Collector to Emitter Breakdown Voltage ( $I_C = 1\text{mA}$ )	400	V
$BV_{ECS}$	Emitter to Collector Voltage - Reverse Battery Condition ( $I_C = 10\text{mA}$ )	28	V
$E_{SCIS25}$	Self Clamping Inductive Switching Energy (Note 1)	300	mJ
$E_{SCIS150}$	Self Clamping Inductive Switching Energy (Note 2)	170	mJ
$I_{C25}$	Collector Current Continuous, at $V_{GE} = 5.0\text{V}$ , $T_C = 25^\circ\text{C}$	41	A
$I_{C110}$	Collector Current Continuous, at $V_{GE} = 5.0\text{V}$ , $T_C = 110^\circ\text{C}$	25.6	A
$V_{GEM}$	Gate to Emitter Voltage Continuous	$\pm 10$	V
$P_D$	Power Dissipation Total, at $T_C = 25^\circ\text{C}$	150	W
	Power Dissipation Derating, for $T_C > 25^\circ\text{C}$	1	W/ $^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to +175	$^\circ\text{C}$
$T_{STG}$	Storage Junction Temperature Range	-55 to +175	$^\circ\text{C}$
$T_L$	Max. Lead Temp. for Soldering (Leads at 1.6mm from case for 10s)	300	$^\circ\text{C}$
$T_{PKG}$	Reflow soldering according to JESD020C	260	$^\circ\text{C}$
ESD	HBM-Electrostatic Discharge Voltage at 100pF, 1500 $\Omega$	4	kV
	CDM-Electrostatic Discharge Voltage at 1 $\Omega$	2	kV

FGB3040G2\_F085 / FGD3040G2\_F085 / FGP3040G2\_F085 / FGI3040G2\_F085

## Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGB3040G2	FGB3040G2_F085	TO-263AB	330mm	24mm	800
FGD3040G2	FGD3040G2_F085	TO-252AA	330mm	16mm	2500
FGP3040G2	FGP3040G2_F085	TO-220AB	Tube	N/A	50
FGI3040G2	FGI3040G2_F085	TO-262AA	Tube	N/A	50

## Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off State Characteristics

$BV_{\text{CER}}$	Collector to Emitter Breakdown Voltage	$I_{\text{CE}} = 2\text{mA}, V_{\text{GE}} = 0,$ $R_{\text{GE}} = 1\text{K}\Omega,$ $T_J = -40 \text{ to } 150^\circ\text{C}$	370	400	430	V	
$BV_{\text{CES}}$	Collector to Emitter Breakdown Voltage	$I_{\text{CE}} = 10\text{mA}, V_{\text{GE}} = 0\text{V},$ $R_{\text{GE}} = 0,$ $T_J = -40 \text{ to } 150^\circ\text{C}$	390	420	450	V	
$BV_{\text{ECS}}$	Emitter to Collector Breakdown Voltage	$I_{\text{CE}} = -20\text{mA}, V_{\text{GE}} = 0\text{V},$ $T_J = 25^\circ\text{C}$	28	-	-	V	
$BV_{\text{GES}}$	Gate to Emitter Breakdown Voltage	$I_{\text{GES}} = \pm 2\text{mA}$	$\pm 12$	$\pm 14$	-	V	
$I_{\text{CER}}$	Collector to Emitter Leakage Current	$V_{\text{CE}} = 250\text{V}, R_{\text{GE}} = 1\text{K}\Omega$	$T_J = 25^\circ\text{C}$	-	-	25	$\mu\text{A}$
			$T_J = 150^\circ\text{C}$	-	-	1	mA
$I_{\text{ECS}}$	Emitter to Collector Leakage Current	$V_{\text{EC}} = 24\text{V},$	$T_J = 25^\circ\text{C}$	-	-	1	mA
			$T_J = 150^\circ\text{C}$	-	-	40	mA
$R_1$	Series Gate Resistance		-	120	-	$\Omega$	
$R_2$	Gate to Emitter Resistance		10K	-	30K	$\Omega$	

### On State Characteristics

$V_{\text{CE(SAT)}}$	Collector to Emitter Saturation Voltage	$I_{\text{CE}} = 6\text{A}, V_{\text{GE}} = 4\text{V},$	$T_J = 25^\circ\text{C}$	-	1.15	1.25	V
$V_{\text{CE(SAT)}}$	Collector to Emitter Saturation Voltage	$I_{\text{CE}} = 10\text{A}, V_{\text{GE}} = 4.5\text{V},$	$T_J = 150^\circ\text{C}$	-	1.35	1.50	V
$V_{\text{CE(SAT)}}$	Collector to Emitter Saturation Voltage	$I_{\text{CE}} = 15\text{A}, V_{\text{GE}} = 4.5\text{V},$	$T_J = 150^\circ\text{C}$	-	1.68	1.85	V
$E_{\text{SCIS}}$	Self Clamped Inductive Switching	$L = 3.0 \text{ mHy}, R_G = 1\text{K}\Omega,$ $V_{\text{GE}} = 5\text{V}, (\text{Note } 1)$	$T_J = 25^\circ\text{C}$	-	-	300	mJ

### Thermal Characteristics

$R_{\theta\text{JC}}$	Thermal Resistance Junction to Case		-	-	1	$^\circ\text{C/W}$
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### Notes:

- 1: Self Clamping Inductive Switching Energy ( $E_{\text{SCIS}25}$ ) of 300 mJ is based on the test conditions that starting  $T_J = 25^\circ\text{C}$ ;  $L = 3\text{mHy}$ ,  $I_{\text{SCIS}} = 14.2\text{A}$ ,  $V_{\text{CC}} = 100\text{V}$  during inductor charging and  $V_{\text{CC}} = 0\text{V}$  during the time in clamp.
- 2: Self Clamping Inductive Switching Energy ( $E_{\text{SCIS}150}$ ) of 170 mJ is based on the test conditions that starting  $T_J = 150^\circ\text{C}$ ;  $L = 3\text{mHy}$ ,  $I_{\text{SCIS}} = 10.8\text{A}$ ,  $V_{\text{CC}} = 100\text{V}$  during inductor charging and  $V_{\text{CC}} = 0\text{V}$  during the time in clamp.

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Dynamic Characteristics**

$Q_{G(ON)}$	Gate Charge	$I_{CE} = 10\text{A}, V_{CE} = 12\text{V}, V_{GE} = 5\text{V}$	-	21	-	nC
$V_{GE(TH)}$	Gate to Emitter Threshold Voltage	$I_{CE} = 1\text{mA}, V_{CE} = V_{GE}, T_J = 25^\circ\text{C}$	1.3	1.7	2.2	V
		$T_J = 150^\circ\text{C}$	0.75	1.2	1.8	
$V_{GEP}$	Gate to Emitter Plateau Voltage	$V_{CE} = 12\text{V}, I_{CE} = 10\text{A}$	-	2.8	-	V

**Switching Characteristics**

$t_{d(ON)R}$	Current Turn-On Delay Time-Resistive	$V_{CE} = 14\text{V}, R_L = 1\Omega$	-	0.9	4	$\mu\text{s}$
$t_{rR}$	Current Rise Time-Resistive	$V_{GE} = 5\text{V}, R_G = 1\text{K}\Omega, T_J = 25^\circ\text{C}$	-	1.9	7	
$t_{d(OFF)L}$	Current Turn-Off Delay Time-Inductive	$V_{CE} = 300\text{V}, L = 1\text{mH}, V_{GE} = 5\text{V}, R_G = 1\text{K}\Omega$	-	4.8	15	$\mu\text{s}$
$t_{fL}$	Current Fall Time-Inductive	$I_{CE} = 6.5\text{A}, T_J = 25^\circ\text{C}$	-	2.0	15	

## Typical Performance Curves

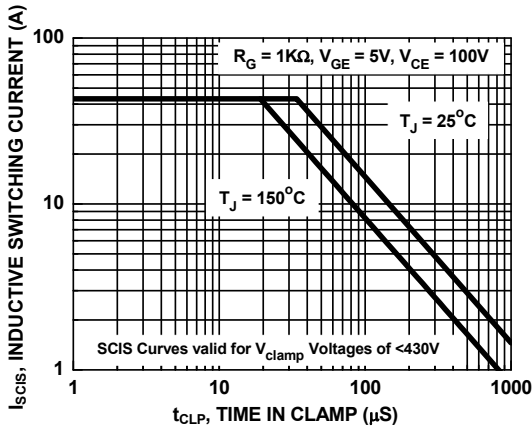


Figure 1. Self Clamped Inductive Switching Current vs. Time in Clamp

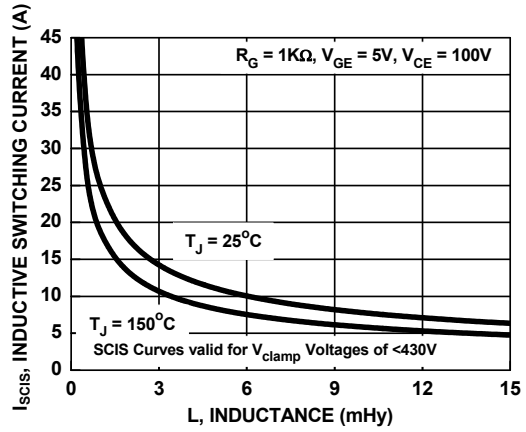


Figure 2. Self Clamped Inductive Switching Current vs. Inductance

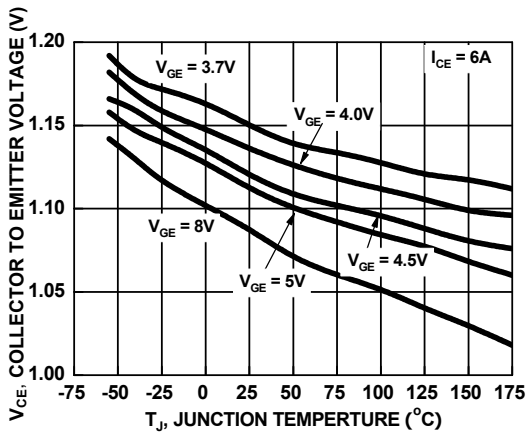


Figure 3. Collector to Emitter On-State Voltage vs. Junction Temperature

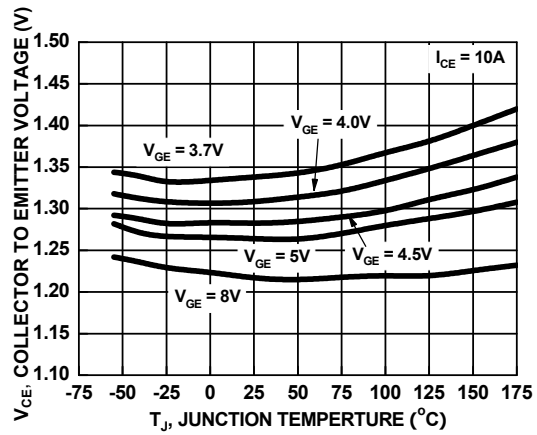


Figure 4. Collector to Emitter On-State Voltage vs. Junction Temperature

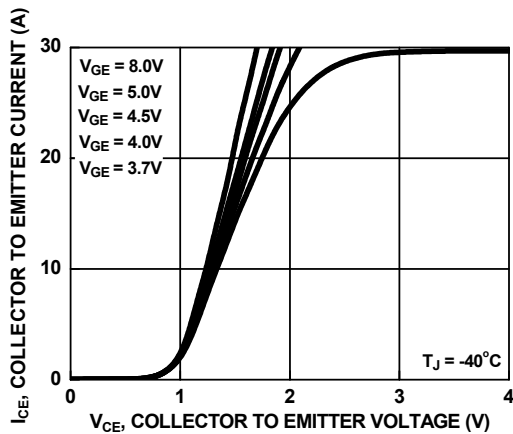


Figure 5. Collector to Emitter On-State Voltage vs. Collector Current

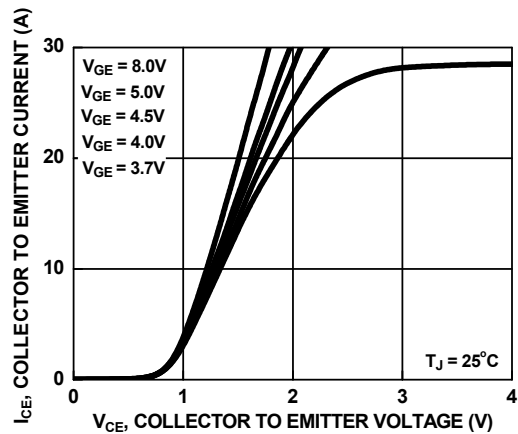
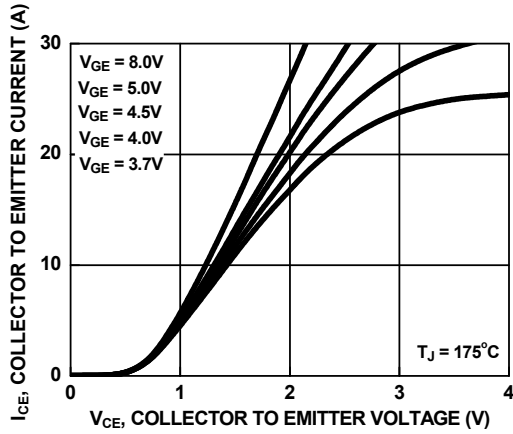
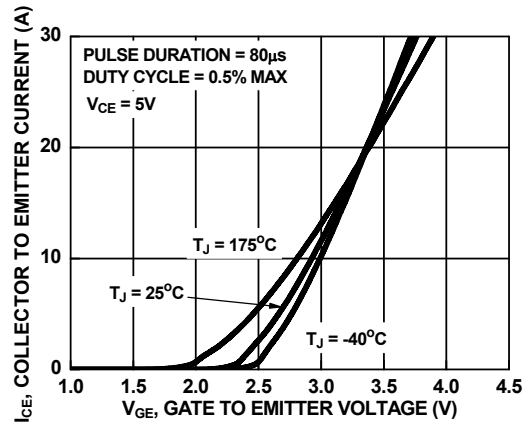


Figure 6. Collector to Emitter On-State Voltage vs. Collector Current

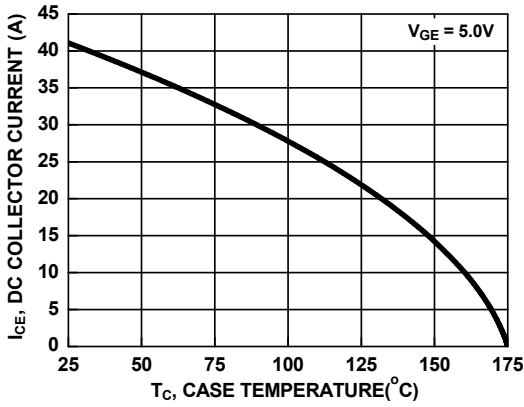
**Typical Performance Curves** (Continued)



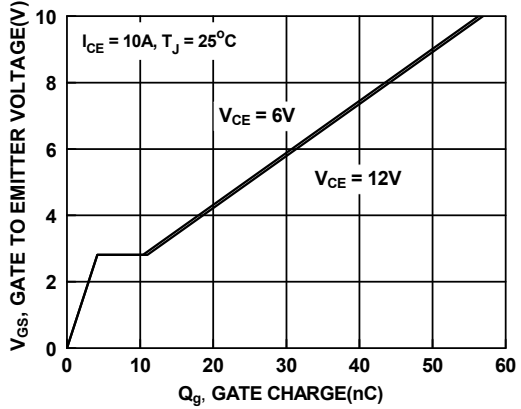
**Figure 7. Collector to Emitter On-State Voltage vs. Collector Current**



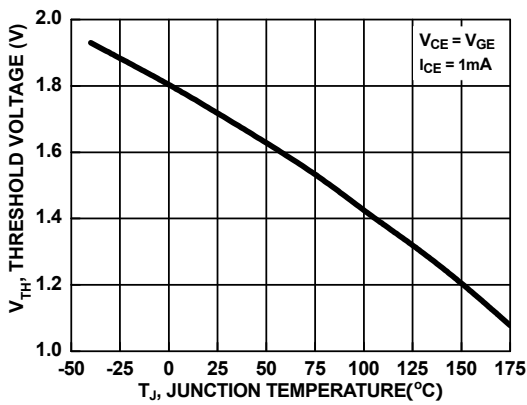
**Figure 8. Transfer Characteristics**



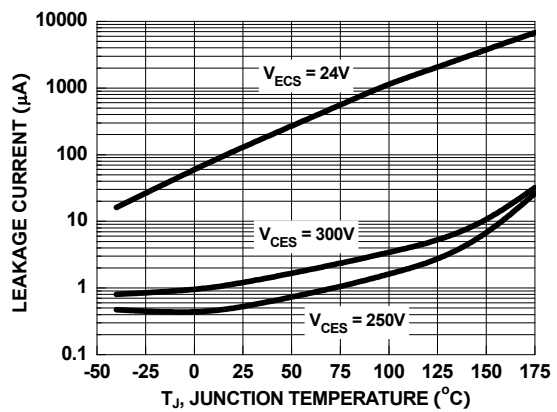
**Figure 9. DC Collector Current vs. Case Temperature**



**Figure 10. Gate Charge**



**Figure 11. Threshold Voltage vs. Junction Temperature**



**Figure 12. Leakage Current vs. Junction Temperature**

Typical Performance Curves (Continued)

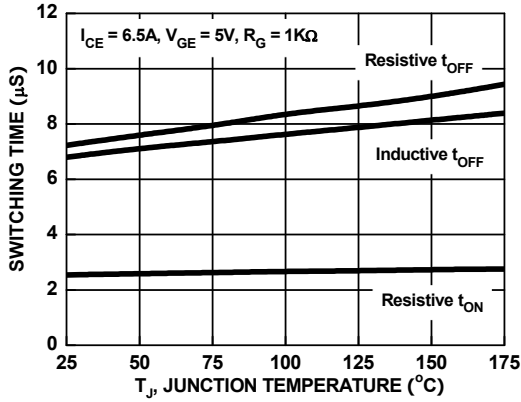


Figure 13. Switching Time vs. Junction Temperature

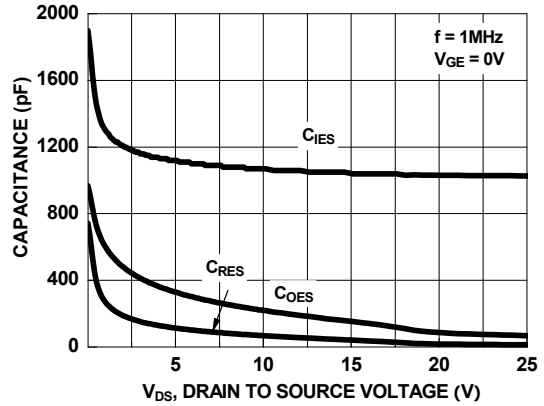


Figure 14. Capacitance vs. Collector to Emitter Voltage

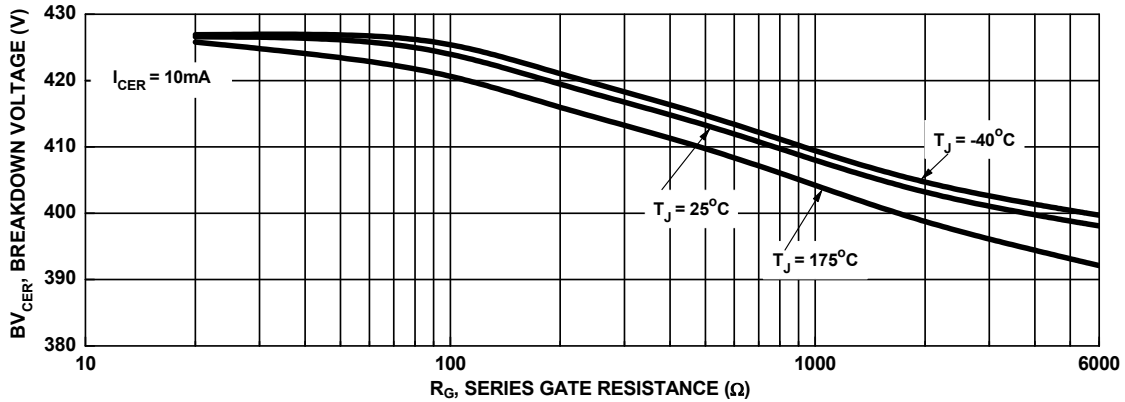


Figure 15. Break down Voltage vs. Series Gate Resistance

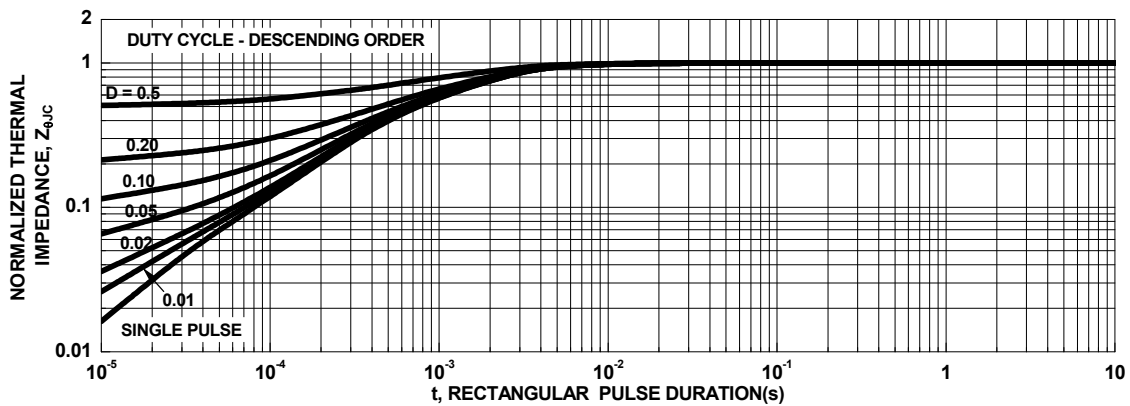
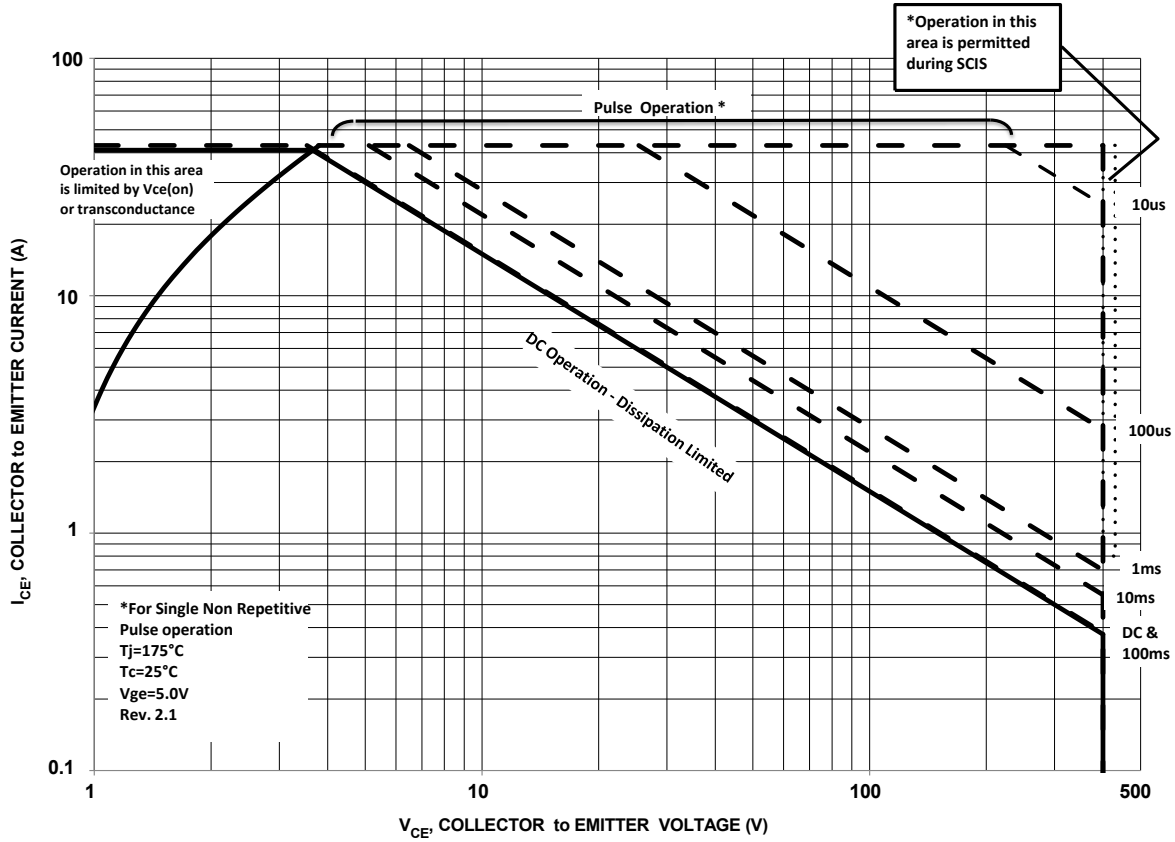


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

### Typical Performance Curves





### Test Circuit and Waveforms

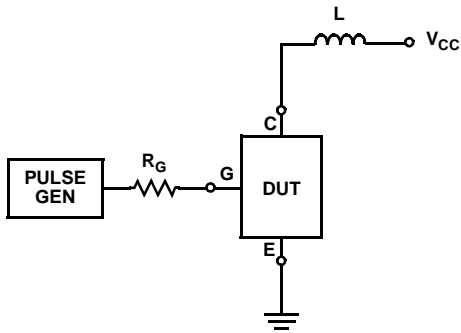


Figure 18. Inductive Switching Test Circuit

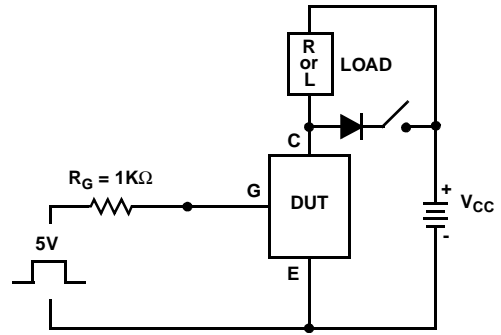


Figure 19.  $t_{ON}$  and  $t_{OFF}$  Switching Test Circuit

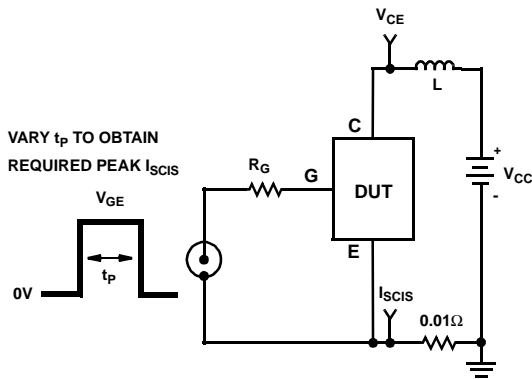


Figure 20. Energy Test Circuit

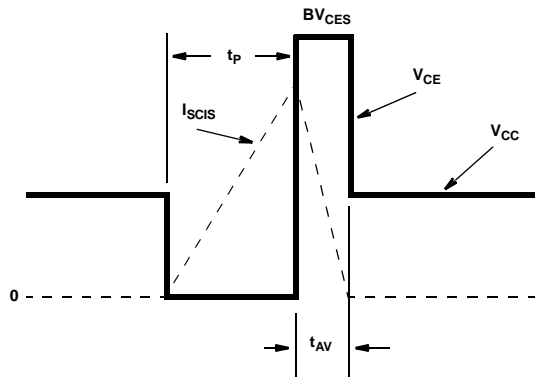







Figure 21. Energy Waveforms



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Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: [org@lifeelectronics.ru](mailto:org@lifeelectronics.ru)